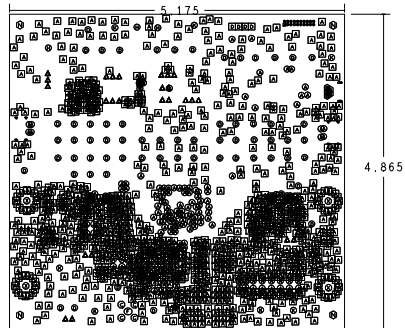
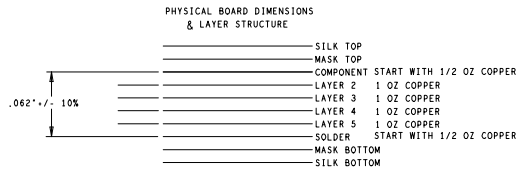


NOTES:

1. THIS IS A 6 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
2. PRINTED CIRCUIT BOARD SHALL BE 1/2 OZ COPPER EXTERNAL LAYERS
1 OZ COPPER INTERNAL LAYERS
BOARD MATERIAL TO BE EXPOXY BASED FR-4.
3. SMOBC SOLDERMASK BOTH SIDES USING BLUE RESIST. IAW IPC-SM-840
4. SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED
INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
5. MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE.
ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS
DIRECTIVE 20002/95/EC
LAMINATE AND RESIN MATERIAL PARAMETERS
Tg > 170 C
Td > 294 C
6. ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
7. MINIMUM TRACE WIDTH 6 MILS/ SPACE 4 MILS

NOTE: All VIAS to be TENTED. NO exposed copper pads on any
VIAS top or bottom Except VIAS in SMT pads.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
⊙	10.0	PLATED	243
⊠	18.0	PLATED	1135
•	23.0	PLATED	19
•	23.0	PLATED	1
•	28.0	PLATED	5
⊙	37.0	PLATED	4
•	40.0	PLATED	64
▲	41.0	PLATED	25
⊠	42.0	PLATED	4
•	65.0	PLATED	3
⊙	65.0	PLATED	1
•	100.0	PLATED	7
•	155.0	PLATED	4
•	128.0	NON-PLATED	4
•	47.24x19.69	PLATED	8
-	76.0x28.0	PLATED	2

TOTAL HOLES: 1529

VIAS in SMT pads need to be epoxy filled.
VIAS in SMT pads need to be epoxy filled.

Drawn By: M.Savio	Date Drawn: 06/01/2023	Engineer: Rahul Ramesh
Released By:	Date Released:	Date Updated:
Updated By:	RTKA489300DE0000BU_REVb_3x3FETs	
	FILENAME:	RTKA489300DE0000BU_REVb_3x3FETs
	SHEET	1 OF 1